

IN THE CLAIMS

Please amend the claims as follows.

1. (Cancelled)
2. (Currently Amended) An IC package as claimed in claim 78 [[1]], wherein the package stiffener includes a copper ring split into power and ground portions, and insulating couplers electrically isolating the power and ground portions of the split copper ring.
3. (Previously Presented) An IC package as claimed in claim 2, wherein the split copper ring mounts on the substrate via a solder with a low resistance path to deliver large amounts of current to the substrate and remove heat from the substrate.
4. (Currently Amended) An IC package as claimed in claim 77 [[1]], wherein the substrate comprises one of a ceramic, a flex, and an integrated circuit printed circuit board (IC-PCB) carrier package.
5. (Previously Presented) An IC package as claimed in claim 4, further comprising one of a pinned grid array (PGA), and a ball grid array (BGA) carrier package.
6. (Previously Presented) An IC package as claimed in claim 4, further comprising one of a flip chip pin grid array (FC-PGA), and a flip chip ball grid array (FC-BGA) carrier package.
7. (Currently Amended) An IC package as claimed in claim 78 [[1]], wherein the package stiffener includes one of electrically conductive, insulating, and intermingled electrically conductive and insulating sections, and one of a molded, stamped, etched, extruded and deposited frame, wherein the stiffener is to withstand temperatures of at least normal IC operation.

8. (Previously Presented) An IC package as claimed in claim 2, further comprising a heat spreader plate bonded to the split copper ring by epoxy and to the die by thermal interface material.

9. (Currently Amended) An IC package as claimed in claim 78 ~~[[1]]~~, wherein the package stiffener is to support at least partially a heat sink.

Claims 10-64. (Canceled)

65. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 ~~[[63]]~~ wherein the frame extends along at least two side edges of the substrate.

66. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 ~~[[63]]~~ wherein the frame is positioned at two separate sections on the substrate.

67. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 ~~[[63]]~~ wherein the frame is positioned at separate corner edges of the substrate.

68. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 ~~[[63]]~~ wherein the frame includes a ring that extends along the perimeter of the substrate.

69. (Previously Presented) An integrated circuit (IC) package as claimed in claim 68 wherein the frame has rounded corners.

70. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 ~~[[63]]~~ wherein the frame and the substrate have similar coefficients of thermal expansion.

71. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 ~~[[63]]~~ wherein the frame has a ground side portion and a power side portion.

72. (Previously Presented) An integrated circuit (IC) package as claimed in claim 71 wherein the ground side portion and the power side portion are separated by insulating couplers.

73. (Previously Presented) An integrated circuit (IC) package as claimed in claim 72 wherein the insulating couplers aid in the structural integrity of the frame.

74. (Currently Amended) An integrated circuit (IC) package as claimed in claim 84 [[63]] further comprising a spreader plate that couples the frame and the die, wherein the frame and the die are between the spreader plate and the substrate.

75. (Previously Presented) An integrated circuit (IC) package as claimed in claim 74 wherein the spreader plate and the frame are integral.

76. (Previously Presented) An integrated circuit (IC) package comprising:
a substrate having a die-side, wherein a die is disposed upon the die-side of the substrate;
a power pod supplying power to the die; and
a package stiffener disposed upon the die-side of the substrate, and spaced from the die to deliver low-inductance current to the die, via the substrate, while concurrently providing stiffening support to the substrate, wherein the package stiffener electrically couples the power pod and the substrate and includes a capacitor.

77. (Currently Amended) An integrated circuit (IC) package comprising:
a substrate supporting at least a die; and
a package stiffener mounted at a perimeter of the substrate, and arranged apart from the die on the substrate to deliver low-inductance current to the die, via the substrate, while concurrently providing stiffening support to the substrate, ~~as claimed in claim 1~~ wherein the package stiffener includes a plurality of cooling fins.

78. (Currently Amended) An integrated circuit (IC) package comprising:
a substrate supporting at least a die; and
a package stiffener mounted at a perimeter of the substrate, and arranged apart from the
die on the substrate to deliver low-inductance current to the die, via the substrate, while
concurrently providing stiffening support to the substrate, as claimed in claim 1 wherein the
package stiffener includes a capacitor.

79. (Previously Presented) An integrated circuit (IC) package as claimed in claim 78
wherein the capacitor includes an insulator.

80. (Currently Amended) An integrated circuit (IC) package as claimed in claim 77
[[1]] wherein the package stiffener includes at least one of a plurality of power ground sections
and a plurality of insulating couplers.

81. (Currently Amended) An integrated circuit (IC) package as claimed in claim 77
[[1]] wherein the package stiffener includes a ground path from the die to the substrate.

82. (Currently Amended) An integrated circuit (IC) package as claimed in claim 77
[[1]] wherein the package stiffener includes a rectangular frame.

83. (Currently Amended) An integrated circuit (IC) package as claimed in claim 77
[[1]] wherein the package stiffener includes a rounded frame.

84. (Currently Amended) An integrated circuit (IC) package ~~as claimed in claim 63~~
comprising:
a substrate having a die-side, wherein a die is disposed upon the die-side of the substrate;
and
a frame disposed upon the die-side of the substrate, and spaced from the die to deliver
low-inductance current to the die, via the substrate, while concurrently providing stiffening
support to the substrate, wherein the frame includes a capacitor.

85. (Previously Presented) An integrated circuit (IC) package as claimed in claim 84 wherein the capacitor includes an insulator.

86. (Currently Amended) An integrated circuit (IC) package ~~as claimed in claim 63~~ comprising:

a substrate having a die-side, wherein a die is disposed upon the die-side of the substrate;
and

a frame disposed upon the die-side of the substrate, and spaced from the die to deliver low-inductance current to the die, via the substrate, while concurrently providing stiffening support to the substrate, wherein the frame includes a plurality of cooling fins.

87. (Currently Amended) An integrated circuit (IC) package as claimed in claim 86 ~~[[63]]~~ wherein the frame includes at least one of a plurality of power ground sections and a plurality of insulating couplers.

88. (Currently Amended) An integrated circuit (IC) package as claimed in claim 86 ~~[[63]]~~ wherein the frame includes a ground path from the die to the substrate.

89. (Previously Presented) An integrated circuit (IC) package as claimed in claim 76 further comprising a plurality of power pods supplying power to the die.

90. (Canceled)

91. (Previously Presented) An integrated circuit (IC) package as claimed in claim 76 wherein the capacitor includes an insulator.